公TDK

July 2017

Chip varistors

ESD/Voltage protection devices

Automotive grade



AVRM, AVR-M series	
AVRM1608/AVR-M1608	JIS 1608 [EIA 0603]
AVRM2012/AVR-M2012	JIS 2012 [EIA 0805]
AVRL series	
AVRL10	JIS 1005 [EIA 0402]
AVRL16	JIS 1608 [EIA 0603]
AVRH series	
AVRH10	JIS 1005 [EIA 0402]

REMINDERS FOR USING THESE PRODUCTS

Before using these products, be sure to request the delivery specifications.

SAFETY REMINDERS

Please pay sufficient attention to the warnings for safe designing when using this products.

▲ REMINDERS

Please pay careful attention to the precautions and follow safe designing practices when using these products.

O Please observe the following precautions in order to avoid problems with chip varistors such as characteristic degradation and element destruction

Please store these products in an environment with a temperature of 5 to 40°C and humidity level of 20 to 70%RH, and use them within six months

Poor storage conditions may lead to the deterioration of the solderability of the edge electrodes, so please be careful to avoid contact with humidity, dew condensation, dust, toxic gas (hydrogen, hydrogen sulfide, sulfurous acid, chlorine, ammonia, etc.), direct sunlight, and so on.

Please do not use products that have been dropped or detached when mounting.

Please solder with the reflow soldering method, and not the flow (dip) soldering method.

O Please observe the following precautions to avoid problems with varistors such as characteristic degradation and element destruction. which ultimately lead to the generation of heat and smoke with the elements.

Do not use in locations where the temperatures exceed the operating temperature range such as under direct sunlight or near sources of heat.

Do not use in locations where there are high levels of humidity such as under direct exposure to weather and areas where steam is released.

Do not use in locations such as dusty areas, high-saline environments, places where the atmosphere is contaminated with corrosive gas, etc.

Avoid powerful vibrations, impact (such as by dropping), pressure, etc. that may lead to splitting in the products.

Do not use with a voltage that exceeds the maximum allowable circuit voltage.

When resin coating (including modular) a varistor, do not use a resin that will cause deterioration of the varistor. Be sure never to use resin that generates hydrogen as palladium is used for the inner electrode.

Avoid attachment near combustible materials.

Please contact our sales offices when considering the use of the products listed on this catalog for applications, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property ('specific uses' such as automobiles, airplanes, medical instruments, nuclear devices, etc.) as well as when considering the use for applications that exceed the range and conditions of this catalog. Please also contact us when using these products for automotive applications.

O As range of catalog, conditions are transcended, or for damage that generated by was used in application specific, etc, accept no the responsibility, wish.

O Please take appropriate measures such as acquiring protective circuits and devices that meet the uses, applications, and conditions of the instruments and keeping backup circuits.

Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

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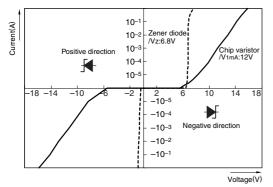
Overview of the AVR series

CHARACTERISTICS OF CHIP VARISTOR

Varistors are voltage dependent nonlinear resistive elements with a resistance that decreases rapidly when the voltage is over the constant value.

Varistors become zener diode of 2 serial connection(Zener Diode) and equivalent, and does not have polarity.

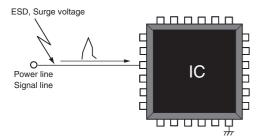
CURRENT vs. VOLTAGE CHARACTERISTICS



THE EFFECT OF THE VARISTOR

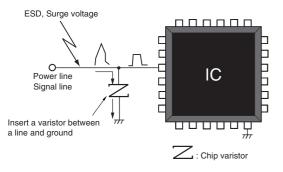
Without varistor

A malfunction and failure of electronic equipment



With Varistor

Suppress abnormal voltage by inserting varistor in a circuit



EQUIVALENT CIRCUIT OF CHIP VARISTORS

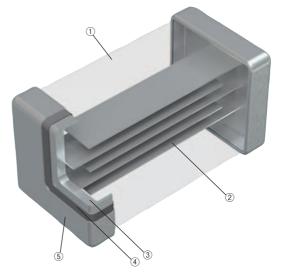


A capacitance content

VEHICLE TARGET TOWARDS CHIP VARISTORS CHARACTERISTICS

- Reliability characteristics evaluated based on AEC-Q200 condition. (except AVRL series)
- O High ESD withstanding voltage
- Small-sized products are available, too
- 125°C Supported

Figure 1 internal structure of multilayer chip varistors



No.	Name	
(1)	Semiconductor ceran	nic
(2)	Internal electrode(Pd))
(3)		Ag
(4)	Terminal electrode	Ni
(5)	_	Sn

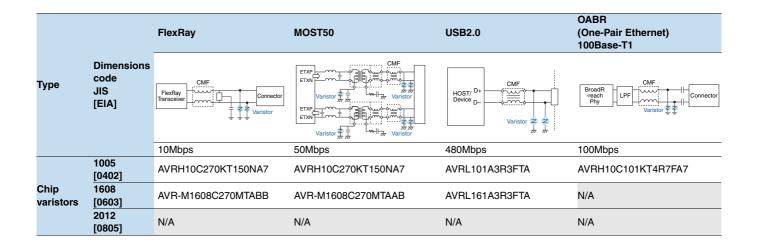
Automotive grade

Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

Overview of the AVR series

COMMUNICATION STANDARD, CIRCUIT EXAMPLE AND COMMUNICATION STANDARD

		Motors	LIN/CXPI	Classical CAN	CAN-FD
Туре	Dimensions code JIS [EIA]		LIN/CXPI Transceiver	CAN Transceiver	CAN Transceiver
		—	20kbps	1Mbps	2-8Mbps
	1005 [0402]	N/A	N/A	AVRH10C270KT150NA7	AVRH10C270KT150NA7
Chip varistors	1608 [0603]	AVR-M1608C270KT6AB	AVRM1608C270KT221M	AVR-M1608C270MTAAB	AVR-M1608C270MTABB
	2012 [0805]	AVR-M2012C390KT6AB	N/A	N/A	N/A





A Please be sure to request delivery specifications that provide further details on the features and specifications of the products for proper and safe use. Please note that the contents may change without any prior notice due to reasons such as upgrading.

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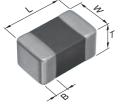
Automotive grade

Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

Overview of the AVR series

PART NUMBER CONSTRUCTION

AVRM	160	8		С		390		K			Т			271		1	١
Series name	L x V dimens (mr	ions	Struct	ure code	Varis	tor voltage (V)		istor vo toleran (%)			kaging	style	inter	citance nal spe ymbol (pF)		toler	itance ance %)
AVRM series		, .6×0.8	(:	General tructure	390	0=39×10 ⁰	ĸ		10	т	Тар	ing	271	=27×10)1	к	±10
	2012 2	.0×1.2	S	structure	220	22	М	±	20	В	Bu	ılk	221	220) —	М	±20
					270 390	27 39	N	±	30	-			271	270)	N	±30
AVR-M	160)8		С		270		М			Т		A	٩AB			
Series name	L x V dimens (mr	ions	Struct	ure code	Varis	tor voltage (V)		istor vo toleran (%)			kaging	style	2	ompany ial sym			
AVR-M series	1608 1	.6×0.8	(:	General tructure	270	0=27×10 ⁰	ĸ	±	:10	Т	Тар	ing					
	2012 2	.0×1.2	3		220	22	М	±	20	В	Bu	lk					
AVRL	10)		1A	390	³⁹	3		F			Т			A		
Series name	L x V dimens (mr	ions ı)		Aaximum nuous volt (Vdc)	age	Capacita (pF)			pacita oleran (pF)		Pack	agin	g style		npany Il symbo	1	
AVRL series		.0×0.5	1A	10		-	3.3	F		-1	T B		bing				
L=Low cap	16 1	.6×0.8				6R8 6	5.8	G	±	2	в	В	ulk				
AVRH	10	0	2	270		K		Т		1	50		Ν		A		7
Series name	L x W dimensions (mm)		cture de	Varisto voltage (V)		Varistor voltage tolerance (%)	Pack	aging	style	•	titance		oacitance Ierance	an IEC61	voltage nount 1000-4-2 kV)	tem	erating perature imit (°C)
AVRH series	10 1.0×0.5	(:	eneral ructure	270=27×1	00	K ±10	т	Tapir	ng		, 15×10 ⁰	N	±30%		25	7	125
H=High Reliability		Su	uciuie	270 27	7 —		В	Bull	<	150	15	F	±1pF				<u> </u>
				390 39 101 10						500 4R7	50 4.7	-	-	_			
				101 10	0				-	4117	4.7	-					



Shape symbol(JIS)	L	W	т	В
1005	1.00±0.05	0.50±0.05	0.50±0.05	0.1min.
1608	1.60±0.1	0.80±0.1	0.80±0.1	0.2min.
2012	2.00±0.2	1.25±0.2	1.00±0.2	0.2min.

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Automotive grade

Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

Overview of the AVR series

OPERATING TEMPERATURE RANGE, PACKAGE QUANTITY, PRODUCT WEIGHT

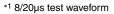
	Temperat	ure range	Package quantity	Individual weight
Туре	Type Operating temperature* Storage temperat (°C) (°C)		(pieces/reel)	(mg)
AVRM1005 AVR-M1005 AVRL10 AVRH10	40 to 1125	40 to +125	10,000	0.6
AVRM1608 AVRL16 AVR-M1608	40 to +125	-40 to +125	4,000	5
AVR-M2012			2,000	13

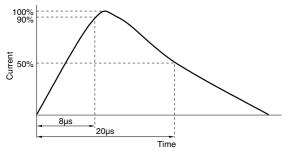
* Operating temperature range includes self-temperature rise.

** The storage temperature range is for after the assembly.

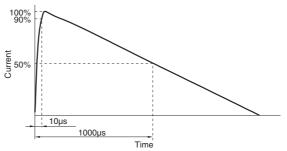
TERMINOLOGY

Item	Unit	Description
Varistor voltage (Breakdown voltage)	V1mA (V)	Chip varistor-terminal voltage when DC1mA was flowed
Maximum continuous voltage	Vdc (V)	DC voltage that is continuously applied between chip varistor terminals Terminal chip varistors leakage current-value: 50µA max Voltage appearing across the varistor when a pulse current (8/20µs*1) of specified peak value is applied.
Clamping voltage	Vcl (V)	Voltage between terminal chip varistors of the Specified peak current value of the impulse current(8/ 20µs*1) is applied
Maximum energy	E (Joule)	When applied specified peak impulse current-value current(10/1000µs*2) once, maximum energy that electrical property of chip varistors be not deteriorated
Maximum peak current	lp (A)	When applied impulse current(8/20µs*1) once, maximum current that electrical property of chip varistors be not deteriorated
Capacitance	C (pF)	Oscillator frequency 1kHz or 1MHz, Capacitance between chip varistor-terminal in oscillator voltage 1Vrms





*2 10/1000µs test waveform



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Automotive grade

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AVRseries (Automotive grade) Product characteristics list

PRODUCT CHARACTERISTICS LIST

Item	V1mA	C1kHz * C1MHz	Vdc	Clamping voltage 8/20µs Pulse	Maximum energy 10/1000µs Pulse	Maximum peak current 8/20µs Pulse	IEC61000-4-2 (Contact)
	(V)	(pF)	DC (V)	Vcl (V)	E (J)	lp (A)	150pF/330 Ω
AVRL101A3R3FTA	27(21.6 to 32.4)	3.3(2.3 to 4.3)*	10	62(0.5A)	0.01	0.5	8kV
AVRL101A6R8GTA	27(21.6 to 32.4)	6.8(4.8 to 8.8)*	10	58(1A)	0.01	1	8kV
AVRL161A3R3FTA	27(21.6 to 32.4)	3.3(2.3 to 4.3)*	10	62(0.5A)	0.01	0.5	8kV
AVRL161A6R8GTA	27(21.6 to 32.4)	6.8(4.8 to 8.8)*	10	58(1A)	0.01	1	8kV
AVRH10C270KT150NA7	27(24.0 to 30.0)	15(10.5 to 19.5)	19	52(2A)	0.02	2	25kV
AVRH10C390KT500NA7	39(35.0 to 43.0)	50(35 to 65)	28	72(2A)	0.02	15	25kV
AVRH10C101KT4R7FA7	100(90 to 110)	4.7(3.7 to 5.7)*	70	190(1A)	0.03	1	25kV
AVR-M1608C220KT2AB	22(19.8 to 24.2)	210	16	37(2A)	0.03	10	25kV
AVR-M1608C220KT6AB	22(19.8 to 24.2)	560	16	34(2A)	0.1	30	25kV
AVR-M1608C270MTABB	27(21.6 to 32.4)	15	17	52(2A)	0.05	2	25kV
AVR-M1608C270MTAAB	27(21.6 to 32.4)	30	17	52(2A)	0.05	2	25kV
AVR-M1608C270KTACB	27(24.0 to 30.0)	60	19	54(2A)	0.05	10	25kV
AVRM1608C270KT800M	27(24.0 to 30.0)	80(64 to 96)	19	53(2A)	0.02	28	25kV
AVR-M1608C270KT2AB	27(24.0 to 30.0)	160	19	42(2A)	0.1	20	25kV
AVRM1608C270KT221M	27(24.0 to 30.0)	220(176 to 264)	19	52(2A)	0.1	40	25kV
AVR-M1608C270KT6AB	27(24.0 to 30.0)	430	19	42(2A)	0.1	48	25kV
AVRM1608C390KT271N	39(35.0 to 43.0)	270(189 to 351)	28	69(2A)	0.1	78	25kV
AVR-M2012C220KT6AB	22(19.8 to 24.2)	800	16	38(5A)	0.3	100	25kV
AVR-M2012C390KT6AB	39(35.0 to 43.0)	430	28	62(5A)	0.3	100	25kV

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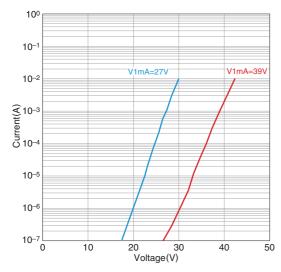
Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

Automotive grade

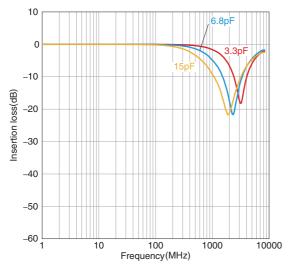
AVRL, AVRH series: JIS1005 [EIA0402] Electrical characteristics

ELECTRICAL CHARACTERISTICS

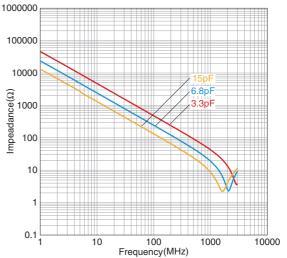
CURRENT vs. VOLTAGE CHARACTERISTICS



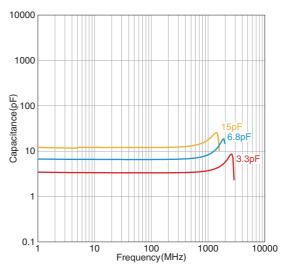
TRANSMISSION CHARACTERISTICS



□IMPEDANCE vs. FREQUENCY CHARACTERISTICS



CAPACITANCE vs. FREQUENCY CHARACTERISTICS



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Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

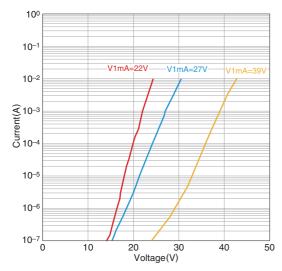
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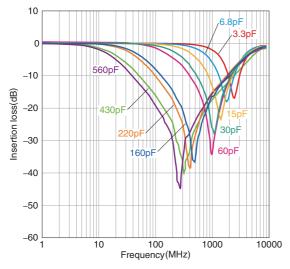
AVRL, AVRM, AVR-M series: JIS1608 [EIA0603] Electrical characteristics

ELECTRICAL CHARACTERISTICS

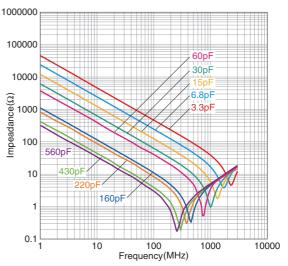
CURRENT vs. VOLTAGE CHARACTERISTICS



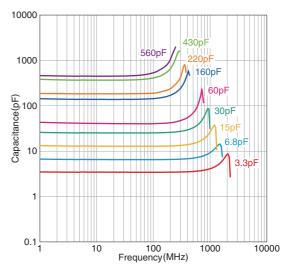
TRANSMISSION CHARACTERISTICS



□ IMPEDANCE vs. FREQUENCY CHARACTERISTICS



CAPACITANCE vs. FREQUENCY CHARACTERISTICS



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Voltage Protection Devices

Chip varistors

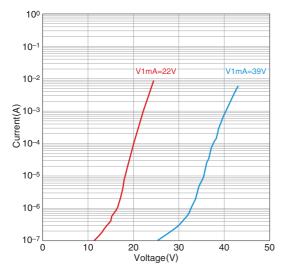
Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

Automotive grade

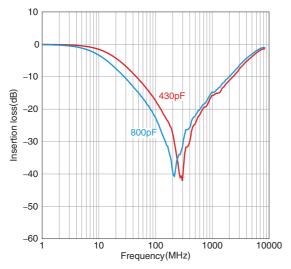
AVR-M series: JIS2012 [EIA0805] Electrical characteristics

ELECTRICAL CHARACTERISTICS

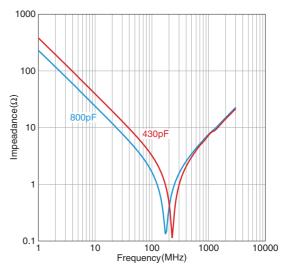
CURRENT vs. VOLTAGE CHARACTERISTICS



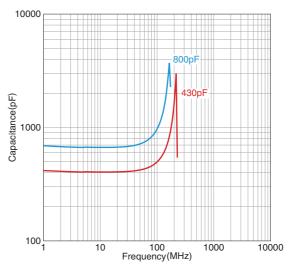
TRANSMISSION CHARACTERISTICS



□ IMPEDANCE vs. FREQUENCY CHARACTERISTICS



CAPACITANCE vs. FREQUENCY CHARACTERISTICS



Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

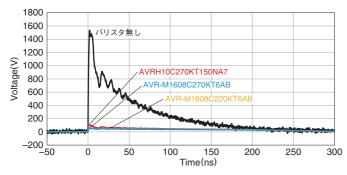
⊗TDK

Automotive grade

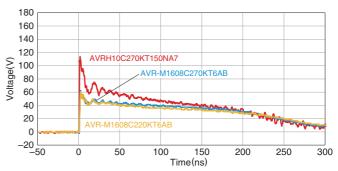
AVR series Electrostatic absorption characteristics

DISCHARGE VOLTAGE WAVEFORM (EXAMPLE)

 $\hfill \square$ WITHOUT VARISTOR, WAVEFORM AT VARISTOR INSTALLATION

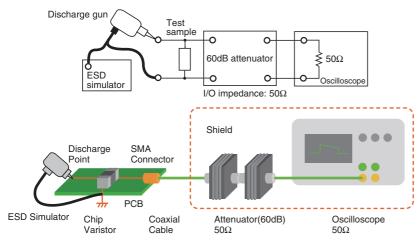


□WAVEFORM AT VARISTOR INSTALLATION



Test conditions
150pF/330Ω (IEC61000-4-2)
Contact discharge, Charged voltage 8kV

TEST CIRCUIT DIAGRAM



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Voltage Protection Devices

Chip varistors

Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

+25kV/-25kV

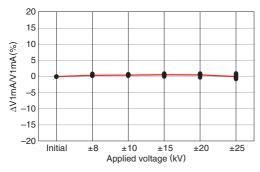
1000

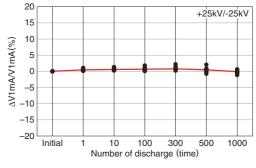
Automotive grade

AVR series Electrostatic discharge tests

APPLIED VOLTAGE STEP(VOLTAGE 10TIMES APPLIED)

□AVRH10C270KT150NA7 (Voltage % change at reference current: within ±10%)





20

15

10

0

-5

-10

-15

-20 Initial

2

Initial

1

10

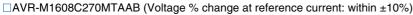
100

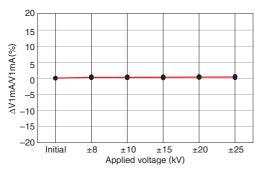
Number of discharge (time)

300

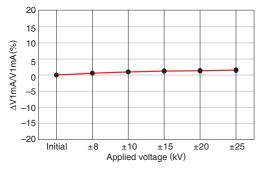
500

ΔV1mA/V1mA(%) 5

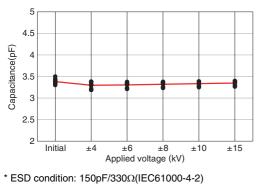


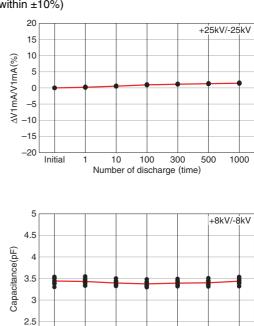


□AVR-M2012C390KT6AB (Voltage % change at reference current: within ±10%)



□AVRL101A3R3FTA(Capacitance: 5pF or less)





10

1

100

Number of discharge (time)

300

500

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■ REPEATED VOLTAGE APPLICATION(~1000 times)

Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

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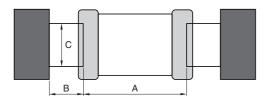
Attention on a circuit board design

Board design

When attached to chip varistors, amount of silver used (fillet size) has direct impact on chip varistors after mounting. Thus, sufficient consideration is necessary.

Set of land dimensions

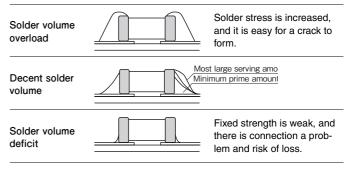
(1) As the stress rises in the chip varistors owing to the increase in silver, breakage and cracks will occur. Cause including crack, as caution on board land design, configure the shape and dimensions so that the amount of silver is appropriate. If you installed 2 or more parts in the Common Land, separated by a solder resist and special land of each component.



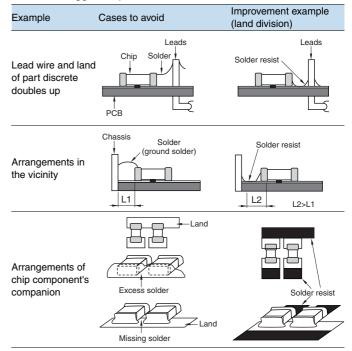
Dimensions shape	Symbol					
Dimensions shape	A	В	С			
1005	0.30 to 0.50	0.35 to 0.45	0.40 to 0.60			
1608	0.60 to 0.80	0.60 to 0.80	0.60 to 0.80			
2012	0.90 to 1.20	0.70 to 0.90	0.90 to 1.20			

(2) When peak levels panning-at soldering is excessive, by solder contraction stress, mechanical-thermal stress causes a Yasuku chip crack. In addition, when the peak level is underestimated, terminal electrode fixed strength is insufficient. This causes chip dropouts and may affect circuit reliability. Representative example of the panning of peak levels is shown in the following.

Recommended silver dose



Case and suggested protocol want to avoid



Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

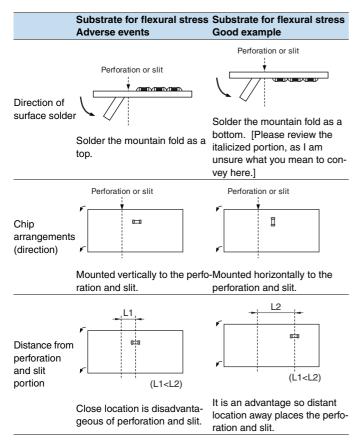
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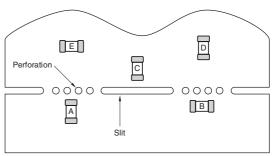
Attention on a circuit board design

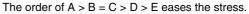
Arrangements of components

(1) I was based on camber of substrate and suggested protocol of chip varistors arrangement, as stress does not join to the utmost is shown in following.



(2) In payment near by board, depending on mount position of chip varistors, as mechanical stress varies, please refer to the following diagram.



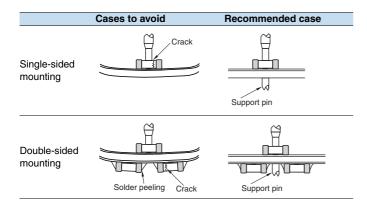


Application to board

Mounting head pressure

Under suction nozzle if dead point too, during implementation, excessive force joins of chip varistors low, as cause causes of crack, please use with reference to something about following.

- Being set to top surface of substrate so that under suction nozzle as for dead center, substrate does not bend back, and adjust, please.
- 2) Nozzle pressure at implementation is 0.1 to 0.3N in static load, please.
- Substrate fixes up back surface of substrate with support pin in impact of suction nozzle to wely deflection to the utmost, and substrate hold deflection, please. A representative example is shown in the following.



Mechanical shock that, if positioning your nail to wear, ragged edge of positionings, participates in chip varistors are locally, and chip varistors, as there is possibility of crack generated, cut the closed positioning, and maintenance and inspection, and, exchange of manage dimensions and position nail periodically, please.

Soldering

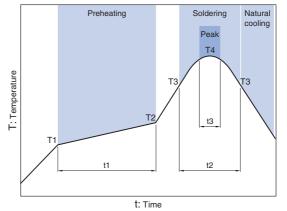
Significant impact is possible on the performance of chip varistors, flux checks something about follow, please use.

(1) Flux uses one with 0.1wt % (Cl conversion) or less halide substance contains amounts, please. In addition, do not do this with strongly acidic objects.

Flux during is soldered (2) Chip varistors is applied the smalleset amount necessary, please.

(3) If Used soluble flux, perform thorough wash particularly, please.

Reflow temperature profile



Specification
For eutectic mixtu

opeenieutien					
For eutectic mixture solder	Use of lead-free solder				
160 to 180°C	150 to 180°C				
200°C	230°C				
240°C max.	260°C max.				
100s max.	120s max.				
30s max.	40s max.				
s2 max.	2 max.				
	For eutectic mixture solder 160 to 180°C 200°C 240°C max. 100s max.				

Soldering iron

The tip temperature and also by (1) types of soldering irons, the size of the substrate, and the geometry of the land pattern. Being earlier, but when as there is possibility that crack occurs in the heat anderson impaction, point soldering iron temperature is high, please do solder work within the following conditions.

Temperature of iron tips (°C)	Wattage (W)	Pallet point shape (mm)	Soldering time (Second)	Frequency
350max.	30max.	ø3.0max.	5 max.	Within each terminal once (Within total of twice)

Direct iron tip is in contact with the (2) chip varistors body, and the strain owing to thermal shock in particular grows even if a crack is generated. Therefore, please do not touch it directly to the terminal electrodes.

Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

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Attention after implementation

Cleaning

(1) If cleaning liquid is inappropriate, residues and other foreign body of fluxes builds up on chip varistors, and can degrade the performance of chip varistors (particularly the insulation resistance).(2) Wash conditions may compromise performance of chip varistors if they are improper (wash due, wash excess).

2-1) For wash due

- (a) By substance of a system in flux residue halide, metal including terminal electrodes may experience corrosion.
- (b) Substance of a system in flux residue halide builds up on chip varistors, and reduces the insulation resistance.
- (c) Soluble flux makes comparisons of colophony series flux, and there is event with trends of significant (1) and(2).

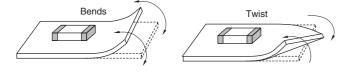
2-2) For excess wash

- (1) Owing to lavage, chip varistors deteriorates, and reduces performance of chip varistors.
- (2) In ultrasonography, when output is passed, substrate resonates size, and crack occurs in body and sprang of chip varistors in vibration of substrate. Since this may reduce the strength of the terminal electrode, please note the following conditions. [Please review the italicized portion, as I am unsure what you mean to convey here.]
 - Ultrasound output Ultrasonic frequency Ultrasound cleaning time

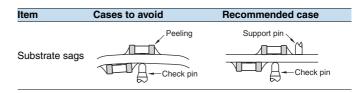
2-3) Concentration including halogen that when cleaning liquid to pollution, when you released is higher, and may cause similar of results into wash due.

Substrate handling after component mounting

(1) When substrate is divided, a flexible so that show in following diagram to substrate, and is given by stress including twist, as there is possibility that crack occurs of chip varistors, please check that stress is within acceptable limits.

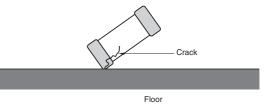


(2) During each substrate operational check, push pressure with contact failure of check pin of boards checkers of check pin may be toned up to be prevented. As substrate is bent under loading, chip varistors is broken owing to stress. There is also the possibility that solder on the terminal electrode will peel off. Follow the diagram for reference, and check that the substrate bends, please.

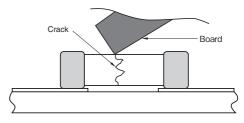


Single-part component handling

To drop impact, as there is possibility that breakage and crack is entered, do not chip varistors that(1) chip varistors falls.



(2) At stacking storage after implementation and treatment of substrate, corner of boards is regarded as chip varistors. Please be careful, as there is the possibility that breakage and cracks will occur on impact.



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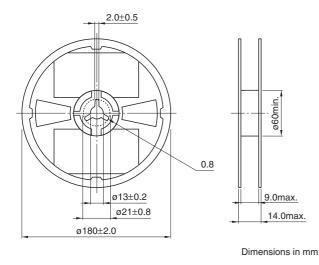
Chip varistors

Automotive grade

Product compatible with RoHS directive Compatible with lead-free solders AEC-Q200

Packaging style

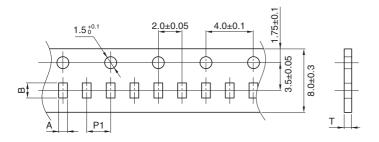
REEL DIMENSIONS



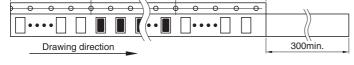
PACKAGE QUANTITY / INDIVIDUAL WEIGHT

Tuno	Package quantity	Individual weight	
Туре	(pieces/reel)	(mg)	
1005	10,000	1.3	
1608	4,000	5.3	
2012	2,000	13.0	

TAPE DIMENSIONS



Dimensions in mn					
Туре	A	В	P1	Т	
1005	0.65+0.05/-0.1	1.15+0.05/-0.1	2±0.05	0.65max.	
1608	1.1±0.2	1.9±0.2	4±0.1	1.1max.	
2012	1.6±0.2	2.3±0.2	4±0.1	1.7max.	
160min. Taping 200min.					



Dimensions in mm